

U.S. DEPARTMENT OF COMMERCE

Rev. 03/ 01)			ent and Trademark Office	
OMB No. 0651-0027 (exp. 5/31/2002)	10239	0524.		JS (INTECH 3.0-059)
To the Honorable Commissioner of Pa	tents and Trademarks: F	Please record the attache	d original docum	ents or copy thereof
Name of conveying party(ies):		2. Name and address	s of receiving	party(ies)
Andy Cowley (08/12/2002), Erdem k (08/12/2002), and Mark Hoinkis (08/ 3.4.0	/12/2002)	Internal Address:	echnologies No	orth America Corp.
Additional name(s) of conveying party(ies) attached?	Yes X No	Street Address: 1730 North First	Street	ت. در
3. Nature of Conveyance:				;; =
x Assignment	Merger			e 6
Security Agreement	Change of Name	City: San Jose		10.
Other		State: CA		Zip: 95112
Execution Date: see Box 1, co	nveying parties	Additional name(s) address(es) attach	&	Yes x No
4. Application number(s) or patent r	number(s):	1037	92116	
If this document is being filed together with A. Patent Application No.(s):	a new application, the ex		- •	August 12, 2002
5. Name and address of party to whor		6. Total number of a		
concerning document should be mailed: Name: Gregory S. Gewirtz		patents involved:		
LERNER, DAVID, LITTENBE MENTLIK, LLP	ERG, KRUMHOLZ &	7. Total fee (37 CFF	₹ 3.41)	\$40.00
Street Address: 600 South Avenue West		X Authorized	to be charged	to deposit account
		Authorized (Form 2038 end	to be charged	to credit card
		8. Deposit account	number:	
City: State: Westfield NJ	Zip: 07090		12-1095	
	DO NOT USE	(Attach duplicate copy	or this page if payi	ng by deposit account)
9. Statement and signature.	DO NOT USE	TIIIG GFACE	· · · · · · · · · · · · · · · · · · ·	
To the best of my knowledge and be is a true copy of the original docume Gregory S. Gewirtz Name of Person Signing		rmation is true and co		ttached copy March 4, 2003 Date
Total number of pages inc	cluding cover sheet, attach	nments, and documents:	4	
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PATENT REEL: 013833 FRAME: 0905

former PTO/SB/15 (8-00) Modified LDLK&M

	Docket Number (Optional)				
ASSIGNMENT OF UTILITY APPLICATION	02 P 11670 US				
	INTECH 1.0-059				
Whereas, I, Andy Cowley					
8 Summerlin Court; Wappingers Falls, New York 12590					
hereafter referred to as assignor, have with others invented certa REDUCTION OF THE SHEAR STRESS IN COPPER DIELECTRIC MATERIAL	in new and useful improvements in VIA'S IN ORGANIC INTERLAYER				
for which an application for a United States Letters Pate Application Number	nt was filed on				
for which an application for a United States Letters Patent was executed by me on Aug. 12, 20					
for which an International Application was filed on	, as				
, designating the United States.					
And					
Whereas, Infineon Technologies North America Corp.					
a corporation of Delaware herein referred to as "assignee" whose	e mailing address is				
1730 North First Street; San Jose, California 95112					
Is desirous of acquiring the entire right, title and interest in the sa	me;				
NOW, THEREFORE, in consideration of the sum of one dollars (\$ 1.00), the receipt whereof is acknowledged, and other good and valuable consideration, I as assignor hereby sell, assign and set over to said assignee my entire right, title and interest for the United States of America and all other countries in and to said invention and the aforesaid utility patent application and all original, divisional, continuation, substitute or reissue applications and patents applied for or granted therefor in the United States of America and all other countries, for said invention, including without limitation all applications and patents for said invention claiming priority or benefit of the aforesaid utility application pursuant to any law or treaty, and including the right to claim such priority or benefit and the Commissioner of Patents and Trademarks is hereby authorized and requested to issue all patents on said improvements or resulting therefrom to said assignee herein, as assignee of the entire interest therein; and the undersigned for me and my legal representatives, heirs and assigns do hereby agree and covenant without further remuneration, to execute and deliver all original, divisional, continuation, reissue and other applications for Letters Patent on said improvements and all assignments thereof to said assignee or its assigns, to communicate to said assignee or its representatives all facts known to the undersigned respecting said improvements, whenever requested, to testify in any interferences or other legal proceedings in which any of said applications or patents may become involved, to sign all lawful papers, make all rightful oaths, and to do generally everything necessary to aid assignee, its successors, assigns and nominees to obtain patent protection for said improvements in all countries, the expenses incident to said applications to be borne and paid by said assignee.					
B/12/62 Date Andy Cowley Witness Erdem Kaltalionly Typed Name of Witness					

forms are submitted.

*Total of

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REEL: 013833 FRAME: 0906

former PTO/SB/15 (8-00) Modified LDLK&M

ASSIGNMENT OF UTILITY APPLICATION	02 P 11670 US INTECH 1.0-059				
	111123111.0 000				
Whereas, I,Erdem Kaltalioglu					
16 F Wintrop Court; Wappinger, New York 12590					
hereafter referred to as assignor, have with others invented certain new and useful improvements in REDUCTION OF THE SHEAR STRESS IN COPPER VIA'S IN ORGANIC INTERLAYER DIELECTRIC MATERIAL					
for which an application for a United States Letters Patent was filed on					
Application Number					
x for which an application for a United States Letters Patent was executed by me on Aug. 12, 2002,					
for which an International Application was filed on, as					
, designating the United	States.				
And					
Whereas, Infineon Technologies North America Corp.					
a corporation of <u>Delaware</u> herein referred to as "assignee" whose	e mailing address is				
1730 North First Street; San Jose, California 95112					
is desirous of acquiring the entire right, title and interest in the sa	me;				
invention and the aforesaid utility patent application and all of applications and patents applied for or granted therefor in the said invention, including without limitation all applications and patents aforesaid utility application pursuant to any law or treaty, at and the Commissioner of Patents and Trademarks is hereby a improvements or resulting therefrom to said assignee herein, undersigned for me and my legal representatives, heirs and as remuneration, to execute and deliver all original, divisional, co Patent on said improvements and all assignments thereof to sassignee or its representatives all facts known to the und requested, to testify in any interferences or other legal proceeding become involved, to sign all lawful papers, make all rightful or assignee, its successors, assigns and nominees to obtain patent expenses incident to said applications to be borne and paid by said	United States of America and all other countries, for atents for said invention claiming priority or benefit of and including the right to claim such priority or benefit uthorized and requested to issue all patents on said as assignee of the entire interest therein; and the signs do hereby agree and covenant without further intinuation, reissue and other applications for Letters aid assignee or its assigns, to communicate to said ersigned respecting said improvements, whenever ings in which any of said applications or patents may the said to do generally everything necessary to aid a protection for said improvements in all countries, the				
8/12/02 5	In Kallaligh				
h	El dom i Ghallogia				
A. C. S					
Withess					
ANDY COWLEY					
Typed Name of Witness					
x *Total of 4 forms are submitted.					

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REEL: 013833 FRAME: 0907

former PTO/SB/15 (8-00) Modified LDLK&M

ASSIGNMENT OF UTILITY APPLICATION	Docket Number (Optional)				
ASSIGNMENT OF STIEFF AFFEIGATION	02 P 11670 US INTECH 1.0-059				
Wherens I Mark Heinkin	-1				
Whereas, I, Mark Hoinkis of					
37 Spruce Ridge Drive; Fishkill, New York 12524					
hereafter referred to as assignor, have with others invented certa REDUCTION OF THE SHEAR STRESS IN COPPER DIELECTRIC MATERIAL	VIA'S IN ORGANIC INTERLAYER				
for which an application for a United States Letters Patent was filed on					
Application Number					
x for which an application for a United States Letters Paten	t was executed by me on Aug. 12, 2002				
for which an International Application was filed on	, as				
, designating the United	States.				
And					
Whereas, Infineon Technologies North America Corp.					
a corporation of Delaware herein referred to as "assignee" whose	e mailing address is				
1730 North First Street; San Jose, California 95112					
is desirous of acquiring the entire right, title and interest in the sa	me;				
NOW, THEREFORE, in consideration of the sum of one is acknowledged, and other good and valuable consideration, I assignee my entire right, title and interest for the United State invention and the aforesaid utility patent application and all of applications and patents applied for or granted therefor in the said invention, including without limitation all applications and patents are provided in the aforesaid utility application pursuant to any law or treaty, at and the Commissioner of Patents and Trademarks is hereby a improvements or resulting therefrom to said assignee herein, undersigned for me and my legal representatives, heirs and as remuneration, to execute and deliver all original, divisional, concepted assignee or its representatives all facts known to the underequested, to testify in any interferences or other legal proceed become involved, to sign all lawful papers, make all rightful of assignee, its successors, assigns and nominees to obtain patent expenses incident to said applications to be borne and paid by said	es of America and all other countries in and to said ariginal, divisional, continuation, substitute or reissue United States of America and all other countries, for atents for said invention claiming priority or benefit of an including the right to claim such priority or benefit authorized and requested to issue all patents on said as assignee of the entire interest therein; and the signs do hereby agree and covenant without further intuition, reissue and other applications for Letters aid assignee or its assigns, to communicate to said tersigned respecting said improvements, whenever ings in which any of said applications or patents may iths, and to do generally everything necessary to aid to protection for said improvements in all countries, the				
8-(2-07 Date	Mark Hornkis Mark Hoinkis				
Argh cower 7 Typed Name of Witness	<u>-</u>				
x *Total of 4 forms are submitted.					

RECORDED: 03/04/2003

PATENT REEL: 013833 FRAME: 0908